

Cheetah / Cougar EVO The smart choice for the smart factory



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Comet Yxlon

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- Headquarters in Hamburg, Germany
- Active in all world markets
- Locations in Shelton (Connecticut), San Jose (California), Yokohama, Shanghai, and Hsinshu (Taiwan)
- Representatives in over 50 countries
- Worldwide at customer sites

Comet Yxlon GmbH is a company of Comet Holding AG. We develop, produce and market high-end X-ray and CT system solutions for industrial and scientific applications - from R&D laboratories to production environments, with integrated services based on artificial intelligence and data analysis.



Our roots go back to Wilhelm Conrad Röntgen



Technical milestones



Global coverage





CHEETAH / Cougar EVO Grand performance for small devices



The Comet Yxlon Cheetah / Cougar EVO feature:

Large flat-panel detectors with up to 50% larger field of view for a better overview and faster working processes due to reduced steps in automated processes.

Best laminography with micro3Dslice, with detailed 3D visualization for quick and easy failure analysis – resulting in substantial cost-savings compared to micro sectioning.

Automatic void calculation with VoidInspect, the laminographybased inspection workflow enabling the rapid non-destructive analysis of voids inside the solder joints of board components.

Integration in the production line: Allows direct communication with inline AOI / AXI inspection systems.

Optional high load capacity (< 20 kg) with reinforced table and mechanics: Several parts and electronic interconnects in fixed packages can be inspected at once – a real-time saver.



CHEETAH EVO X-ray technology at its best



Technical Specifications

- 460 x 410 mm inspection area
- 800 x 500 mm sample size
- Open X-ray tube with TXI
- 64 W tube power, 10 W target power
- 15 W target power with HighPowerTarget
- Collision-free design
- Oblique angle viewing ±70°
- x3000 geometrical magnification
- CL and $\mu\text{CT}\text{-}\text{capabilities}$ incl. Y.QuickScan®
- Flat-panel detector as standard
- 16 bit real-time image processing
- Advanced manipulation
- Air cushioning in all moving parts



CHEETAH EVO X-ray technology at its best





Cougar EVO X-ray technology at its best



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Technical Specifications

- 310 x 310 mm inspection area
- 440 x 450 mm sample size
- Open X-ray tube with TXI
- 64 W tube power, 10 W target power
- 15 W target power with HighPowerTarget
- Collision-free design
- Oblique angle viewing ±70°
- x2000 geometrical magnification
- CL and $\mu\text{CT}\text{-}\text{capabilities}$ incl. Y.QuickScan®
- Flat-panel detector as standard
- 16 bit real-time image processing
- Smallest Footprint 1100 x 1100 mm

Cougar EVO X-ray technology at its best





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Advantage:

The inner workings of the system can be accessed by the front, so there is no service door on the back and the system can be placed with the back directly against the wall.

Benefits

Best image in shortest time

Microfocus X-ray system for non-destructive testing featuring **highest resolution and magnification** (feature detectability < 1 μ m). Zoom+ for brilliant images and faster inspection without tube adjustments or software interpolation. The **eHDR-filter** enables the contrast within an X-ray image to be emphasized dependent on the image content and realizes sharp high-quality images.

All X-ray options on the smallest footprint

2D scans, laminography and even CT.

Ease of use with 1-click solutions

1-click operation for rapid inspection with advanced technological functions e.g. *Click & Centre* and Frame & Zoom. Wizard guided functions to perform simple inspections. Automated inspection workflows.

Stable image quality

Air suspension against unwanted vibrations. (Cheetah only)



Deeper insights

With the high-resolution digital detector option, a superior detail detectability of less than 0.5 microns can be achieved.

Laminographic scans with highest magnification and ±70° oblique viewing result in high-quality 2.5D results.

Automatic tracing of the sample (AIM)

AIM-technology when pivoting the detector or rotating the sample, details under inspection remain in the middle of the image.

Variety of applications

Due to the optional 20kg "High load capacity" packages, the system provides a higher flexibility. (Cheetah only)

Automatic inspection for on-site applications

Generation of automatic inspection procedures by intuitive teach-in concept.

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Common inspection tasks



Semiconductor Wire Bonds

Laminography



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Common SMT inspection tasks



Void inspection



BGA

BGA

Printed Circuit Board (PCB) Laminography





Common SMT inspection tasks





Common THT inspection tasks

THT Inspection



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Through Hole Technology (THT) Voiding

Laminography ***



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CT Scan of Battery Cell





Features

(Depending on the machine configuration)





Open X-ray tube with micro-/multifocus

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- Open tube design
- Microfocus or Multifocus (MFT)
- Optional MFT offering 3 modes:
 - Nanofocus for highest
 resolution with target power <1
 W
 - Microfocus for standard microfocus applications up to 3W target power
 - **High-Power** for the inspection of denser materials with up to 15 W with High-Power Target
- TXI True X-ray intensity control
- 64 W tube power
- Detail detectability down to <350 nm

Benefits of open microfocus tubes

- Unlimited lifetime Filament & target changable Various target materials:
- High Power
- High Magnification
- High Resolution





True X-ray Intensity (TXI)



Image without TXI

Image with TXI

- True X-ray Intensity immediate and steady X-ray stability after auto-start
- Measures the power at the target for more efficient control of focal-spot size
- Constant image qualtiy = repeatable results

Patented Comet YxIon Technology



Water-cooled FXT 160.51



Permanent stabilization of the focal spot due to improved heat dissipation at the tube optics leads to improved CT results with higher spatial resolution and less image distortion. Available as upgrade.

Benefits for your testing environment

• Improved spatial resolution enhances CT capabilities of existing system configuration without changing hardware configuration

Advantages for your Cheetah / Cougar operators

Continuation of existing workflows without the necessity of additional training

Requirements

• Cheetah EVO with System Version v5 and FXT160.51 X-ray tube

C•met A stabilized focal spot significantly increases CT detail resolution

without cooling

with cooling



Tube Technology





Y.High Power Target

- 5 µm tungsten layer
- Offers a resolution at high-power factor 2-3x higher compared to standard targets

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- Optimum target for applications at high target power with high resolution
- Max. target power: 15 W

Y.High Resolution Power Target (HRP-Target)

- 1 µm tungsten layer
- Offers a resolution at nanofocus factor 2x higher compared to standard targets until 8 W
- Optimum target for applications with highest resolution
- Max. target power: 15 W

Comparision Standard vs High Power Target





At same tube and detector settings

Detector Technology





- Large flat-panel detectors 1515 or 1616.
 Better overview and shorter inspection times due to reduced steps in automated routines
- Pixel size optimized for resolution and contrast sensitivity even with limited or no image integration
- Fast real time imaging, 34 fps (1x1)
- 16 bit image processing 65000 grey values
- Spatial resolution in combination with FXT-160.51
 Multifocus tube of 0,6µm (JIMA mask)



FPD: High image quality with lower dose

Benefit:

Minimized damage on sensitive components by using lower kV and power at the same image quality









Dose reduction kit

Protect sensitive parts by reducing most damaging low-energy photons



- With optional dose reduction kit the dose rate on sensitive components can be additionaly reduced.
- Combination of collimator and filters limit the effects of radiation to potentially damage silicon components while allowing allowing exact the radiation needed for imaging.

Dose Monitoring

Dose Monitoring technology for Cheetah EVO systems in order to avoid harming of electronics parts which are sensitive to X-rays. / Dose monitoring technology for Cheetah EVO systems to prevent damage of X-ray sensitive electronics

Benefits

- X-ray inspection of components without destroying them if possible.
- Better inspection planning in compliance with specified dose limits is possible.
- Components that may have been destroyed or whose function has been impaired can be identified and sorted out.

Advantages

X-ray dose is automatically monitored, and the operator is informed when a critical threshold is reached, and the scan is aborted; this guarantees a non-destructive inspection of sensitive parts.

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Dose Monitoring & Alarm in Cheetah

Current & accumulated dose warning levels prevent damage to sensitive parts





Advanced Manipulation Alternative Trays

3 different exchangeable trays \rightarrow **Increase of flexibility**



Standard tray

Rotational tray

µCT-sample tray



Collision-free concept (guard)



5-axis Manipulation System

- x/y sample tray axis
- z tube axis
- Detector 140° tilt angle
- z detector axis
- 360° rotational sample table



µCT Rotation Axis

- Reconfiguration in <1 min.
- CT-upgradable on customer site

Optional 20 kg "High Load Capacity"



- Flexibility to inspect heavier objects such as controller box for electric vehicles.
- Durable and stable manipulator through improved tray and guides, High Load Capacity for your empowerment.
- With the optional high load capacity unit on the Comet Yxlon Cheetah EVO, we are closing a gap that greatly expands the flexibility of the microfocus X-ray and CT system.
- While common quality inspections in the manufacturing electronics industry such as SMT usually get by with a maximum loading of the inspection part carrier of 2 5 kg, the high loading capacity of up to 20 kg offers fundamental advantages.



High Load Capacity

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Software / Image Processing

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Intuitive FGUI software to control all system functions and components

- X-ray Parameter, X-ray on/off, X-ray tube settings
- Maniplation system and axis via Mouse or joysticks
- Image-enhancement, -improvement and –processing functions, such as:
 - Contrast enhancement or auto contrast
 - Sharpening Filter
 - Averaging
 - Color Filter
 - Void Calculation
 - BGA Inspection
 - ...and many more



1-click Solutions





- 1-click to first image
- Click & Center
- Frame & Zoom
- Click & Fly
- 1-click access to library of automated inspection routines
- 1-click access to CL/µCT workspace with execution (option)

Y.FGUI Overview





eHDR – Filter



1-click operation – electronic High-Dynamic Radioscopy (eHDR)

Real-time imaging with outstanding effects



Memory device



Crack in wedge bond

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Easy automation and automatic defect recognition

Customer benefits:

- Teach-in with FNC programming based on easy visual basics
- Fully automated functionality without needing CAD Input or programming skills
- Simple to make and modify, accurate automated inspection routines
- Automated component fault analysis
- Easy-to-apply, powerful suite of image enhancements
- Automated reports

Comet YxIon Inspection pool:

- Collection of inspections
- Easily re-useable
- Includes machine settings

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- Works with BGA and Multi Area Void calculations
- Can be integrated into automated inspection plan



FGUI Automatic BGA Inspection

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Wizard leads user through inspection workflow

Automatic grid detection

Solder balls can be deselected / selected manually

- Either by clicking on the respective ball
- Or by drawinig a rectangle around respective balls

Balls will be indexed automatically for clear identification

Automatic detail examination in high magnification

X-Ray High Power -	тхі	X-Ray OFF
	Voltage 90 kV Current 45.9 µA	ON OFF
Inspection pool		
Inspections		
Inspection configuration BGA_Insp2 Type : BGA Description : BGA Step 1 : Overview Step 2 : Restore Po		

FGUI Automatic Analysis MAVC





- Automatic Analysis of Multi Void Areas
- Each area can be calculated independently
- Each area can have own defect criteria





Traceability

Establish a one-to-one correspondence between

- Samples and
- Inspection Reports / Inspection Maps

Barcodereader & holder

ID and 2D codes

Y.FGUI plugin

- 3 user guidance modes:
 - Always / Before Inspection:
 - Mandatory report generation
 - Forces user to enter ID
 - Optional / After Inspection:
 - E.g. Report generation for failed samples only
 - Never:
 - No traceability



e and	
the next sample before	e closing the door.
Clear	Ok
	e and the next sample before Clear

FGUI 1- Click Inspection Report





- Automatic manipulation to ROIs
- Manual Good / Bad decision marks by
- Automatic generated Good / Bad marks



High-performance/fast Computed Tomography and Laminography inspection

Benefits:

- µCT results in few minutes including image acquisition and CT reconstruction
- Easy and intuitive wizard for CT and CL
- Various algorithms to enhance the reconstruction including jitter correction
- Slice-by-slice image analysis
- Superior CL and µCT results



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Laminography: Combining the benefits of 2D and 3D inspection

Computed laminography (micro3D Slice):

- "2.5D inspection"
- Technological intermediate between 2D X-ray radioscopy and 3D computed tomography (CT).

Laminography addresses the specific challenges of inspecting flat components, such as printed circuit boards (PCB), microchips (IC), entire cell phones, tablets, laptops, or even scripts on papyrus.

While a 2D X-ray inspection provides high resolution but does not give spatial information, 3D CT supplies good spatial information but can lack resolution.

A case for laminography: It adds depth information to highresolution 2D images, so defects can be reliably detected and spatially located in a plane object.



micro3D slice

Reconstruction of projections (DR X-ray images) obtaining a incomplete set of data by rotating the object on sample tray (360°). Precondition is the penetration capability of the inspected object from reduced angles (< 60°).

Used for flat components or larger size objects to obtain higher magnification images and CT Slices

Allows to inspect single 3D slices

Software add-on for Cheetah and Cougar. No need for specific hardware.





Analysis Software (Depending on the machine configuration)





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Image Software Solutions

For visualization and image analysis, Cougar and Cheetah offer:

- 2D X-ray image inspection: Comet Yxlon FGUI
- **CT reconstruction and visualization:** Comet Yxlon FF CT software (powered by Siemens CERA Xplorer)
- **3D volume visualization and analysis:** Dragonfly
- CT data processing, analysis, and visualization: Volume Graphics VGSTUDIO

Software solutions for automated inspection

- Multi Area Void Calculation MAVC
- Automatic positioning and re-positioning of inspection parts based on their unique structures
- Automated inspection processes for identical parts after an initial manual set-up by an operator
- Easy reporting and software-supported evaluation
- VoidInspect CL for void analysis in computed laminography images

Facts & Figures





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Cheetah EVO

X-ray inspection system		General Product Features	
Dimensions (w x d x h)	1,650 x 1,400 x 2,050 mm	Time to first image (typ.)	~ 10 s
Weight	2,200 kg	Reconfiguration time (typ.)	< 60 s
Mains connections	230 V ± 10% AC, 50/60 Hz, 1 Phase, neutral and ground conductor	Acquisition time (Quick Scan) for 2000 projections	- 3.15 min
Fuse protection	16 A	Reconstruction time	
Max. power consumption	2.5 kVA	(Quick Scan)	~ 1.55 min
Max. dose rate*	< 1µSv/h	for 2000 projections	
* at 100 mm distance to the cat	vinet surface	Acquisition time (micro3Dslice Semicon) for 120 projections	- 1.45 min
inspection pures		Reconstruction time	
Max. part size	800 x 500 mm (31" x 19")	(micro3Dslice Semicon)	~ 0.30 min
Max. radiographic area	460 x 410 mm (18" x 16")	for 120 projections	
Max. part weight (standard)	5 kg	Access for sample loading	large automated door (690 x 650 mm)
Max. part weight	2 kg	2 kg	
Max. part weight	20 kg	Monitor	2/" Ultrasharp, wide viewing angles
(high load capacity)	20	Zoom+	yes
Manipulation		PowerDrive	yes
		Image stabilization	air suspension
Manipulation control	via mouse or joystick		
Manipulation axes	X, Y, Z(D)*		
Oblique viewing	+/-70° (140°)		
* Manipulation options for horiz	ontal and vertical rotation		

available

X-ray source	FXT-160.50 Microfocus	FXT-160.51 Multifocus
Target	transmis	ssion
Voltage range	20 - 160	0 kV
Current range	0.001 – 1.	.0 mA
Tube power	max. 64	4 W
Target power	max. 15	5 W
Target material	Tungst	ten
Detail detectability	0.75 µm	< 0.3 µm
X-ray intensity control	TXI	
Optional		Water-cooling
Optional	Dose Reduction Kit with collimator	r and filters for sensitive test parts

Image Chain

Geometric magnification		- 3,000 x	
Total magnification		- 384,000 x	
Spatial Resolution	1.5 µm		0.6 µm

Flat-panel detector	1308	1313	1515	1616
Max. resolution Pixel	1004 x 620	1004 x 1004	1280 x 1280	1276 x 1276
Pixel size	127 µm	127 µm	119 µm	127 µm
Pixel Area	128 mm x 79 mm	128 mm x 128 mm	152 mm x 152 mm	162 mm x 162 mm
A/D transformer			16 bit	





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Cougar EVO

X-ray inspection system

General Product Features
Time to first image (typ.)

~ 10 s

< 60 s

Dimensions (w x d x h)	1,000 x 1,050 x 2,200 mm	Time to first image (typ.)
Weight	1,450 kg	Reconfiguration time (typ.)
Mains connections	230 V ± 10% AC, 50/60 Hz, 1 Phase, neutral and ground conductor	Acquisition time (Quick Scan)
Fuse protection	16 A	for 2000 projections
Max. power consumption	2.5 kVA	(Quick Scan)
Max. dose rate*	< 1µSv/h	for 2000 projections
* at 100 mm distance to the cabin	et surface	Acquisition time

Inspection parts

Max. part size	440 mm x 550 mm (17" x 21")
Max. radiographic area	310 mm x 310 mm (12" x 12")
Max. part weight (standard)	5 kg
Max. part weight rotation and tilt	2 kg

Manipulation control	via mouse or joyst			
Manipulation axes	X, Y, Z(D)*			
Oblique viewing	+/-70° (140°)			

cquisition time - 3.15 min vick Scan) r 2000 projections econstruction time - 1.55 min vick Scan) r 2000 projections equisition time (micro3Dslice Semicon) - 1.45 min for 120 projections Reconstruction time (micro3Dslice Semicon) - 0.30 min for 120 projections Access for manual ample loading 380 mm x 200 mm Cabinet window 27" Ultrasharp, Monitor wide viewing angles Zoom+ yes PowerDrive ick yes

* Manipulation options for horizontal and vertical rotation and

tilting available

X-ray source	FXT-160.50 Microfocus	FXT-160.51 Multifocus	
Target	transmissi	on	
Voltage range	20 – 160 kV		
Current range	0.001 – 1.0 mA		
Tube power	max. 64 W		
Target power	max. 15 W		
Target material	Tungsten		
Detail detectability	0.75 μm < 0.3 μ		
X-ray intensity control	TXI		
Optional	Dose Reduction Kit with collimator and filters for sensitive test parts		

Image Chain

Geometric magnification	~ 2,000 x	
Total magnification	- 384,000 x	
Spatial Resolution	1.5 µm	0.6 µm

Flat-panel detector	1308	1313	1515	1616
Max. resolution Pixel	1004 x 620	1004 x 1004	1280 x 1280	1276 x 1276
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A/D transformer			16 bit	



Please note that not all components and features described in this brochure belong to the standard configurations but are part of an optional selection.

Life Cycle Service

Supporting you every step of the way

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 ON-Site Service Installation & Commissioning Output Output Second Particle Control Contr	Remote-Service Remote Control VisualAssist 	 Upgrades 9. System Releases 9. Components (e.g. Detectors) 9. Operating Software Detectors Content Conten
	 Field Service Preventive Maintenance Calibration & Certification Repair & Exchange 	
	 Service Level Agreements Sampling Inspection At-line Inspection In-line Inspection Warranty Extension 	
	Service Parts Smart Service Parts Smart Service Cases 	



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Thank you for your attention

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